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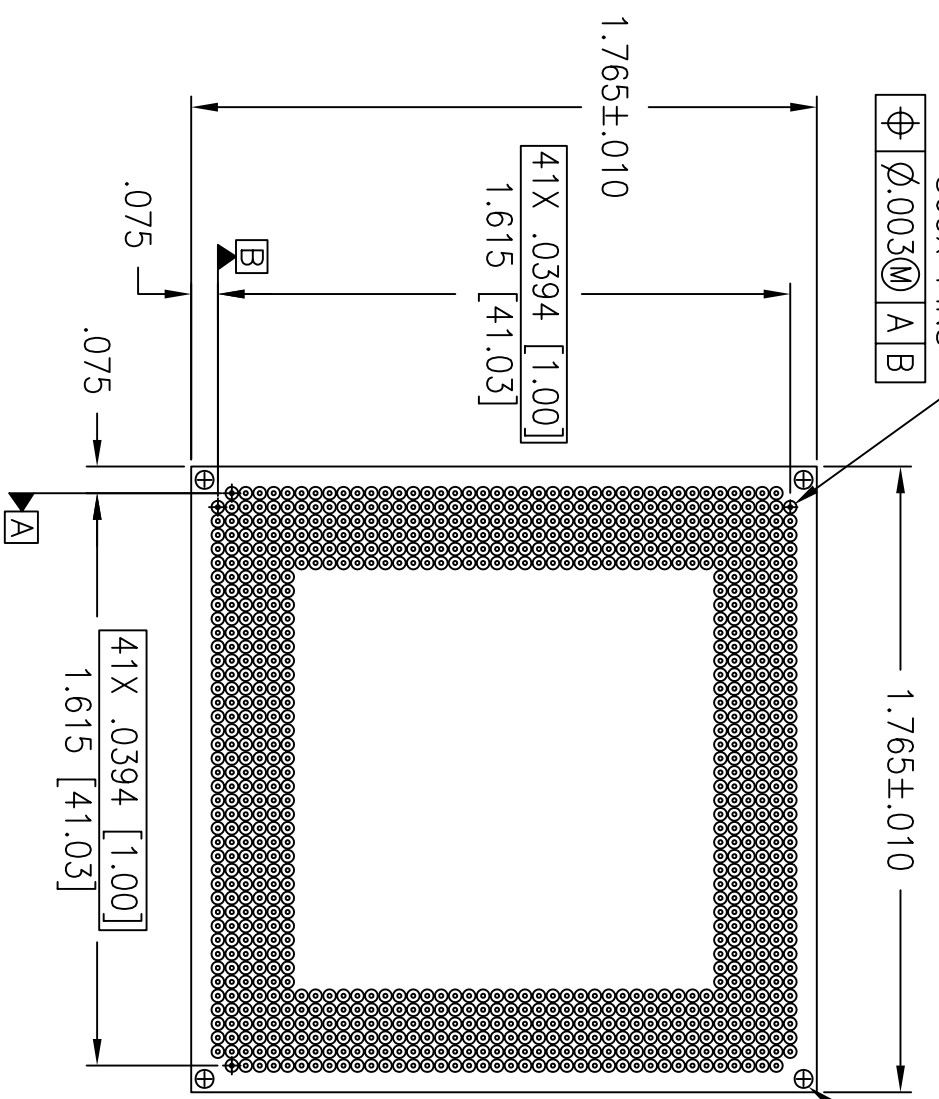
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2

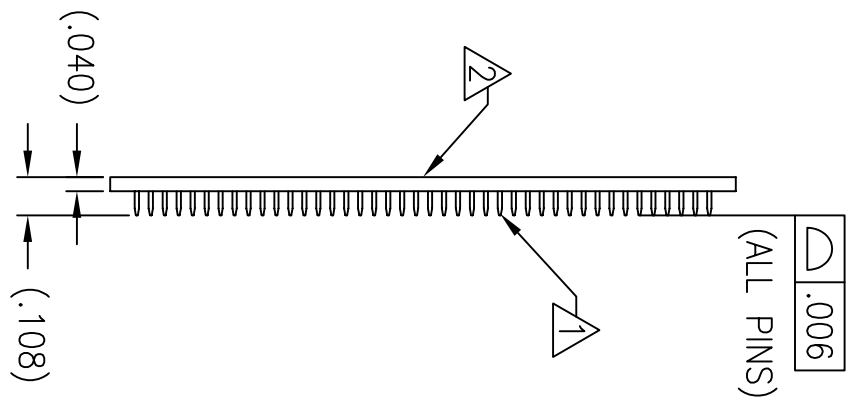
1

REV	DESCRIPTION	REVISIONS	EON	DATE	RELEASE
1	SALES RELEASE				

TOP VIEW



RS VIEW



NOTES:

1. PINS Ø.0117
MATERIAL: PHOSPHOR BRONZE.
PLATING: HARD GOLD OVER NICKEL.
2. INSULATOR MATERIAL: FR4.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES [ALTERNATE] DIMENSIONS ARE IN MILLIMETERS		CONTRACT NO.		TITLE	
TOLERANCES:	±	DATE	DATE	DATE	DATE
ANGLES:	± 1/64	DESIGNER	CHECKER	PROCESS ENG.	DATE
FRACTIONS:	4/10	DATE	DATE	DATE	DATE
DECIMALS:	.XX	DATE	DATE	DATE	DATE
XXX	±.005	DATE	DATE	DATE	DATE
XXXX	±.0005	DATE	DATE	DATE	DATE

<p>INTERCONNECT SYSTEMS INC. 708 VIA ALONDRA, CAMARILLO, CA 93012</p>		<p>Hilo-BGA PIN BASE 42 X 42, 860 PINS 1mm PITCH</p>	
SIZE	A	SCALE	N/A
SAVED AS:	HLP-420860-10.DWG	FINISHED ASST:	HLP-420860-B-10
DRAWING NO.	HLP-420860-B-10	REV	1

ASIZE 4 3 2 1